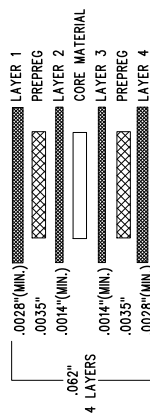
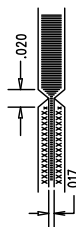


LAYER STRUCTURE

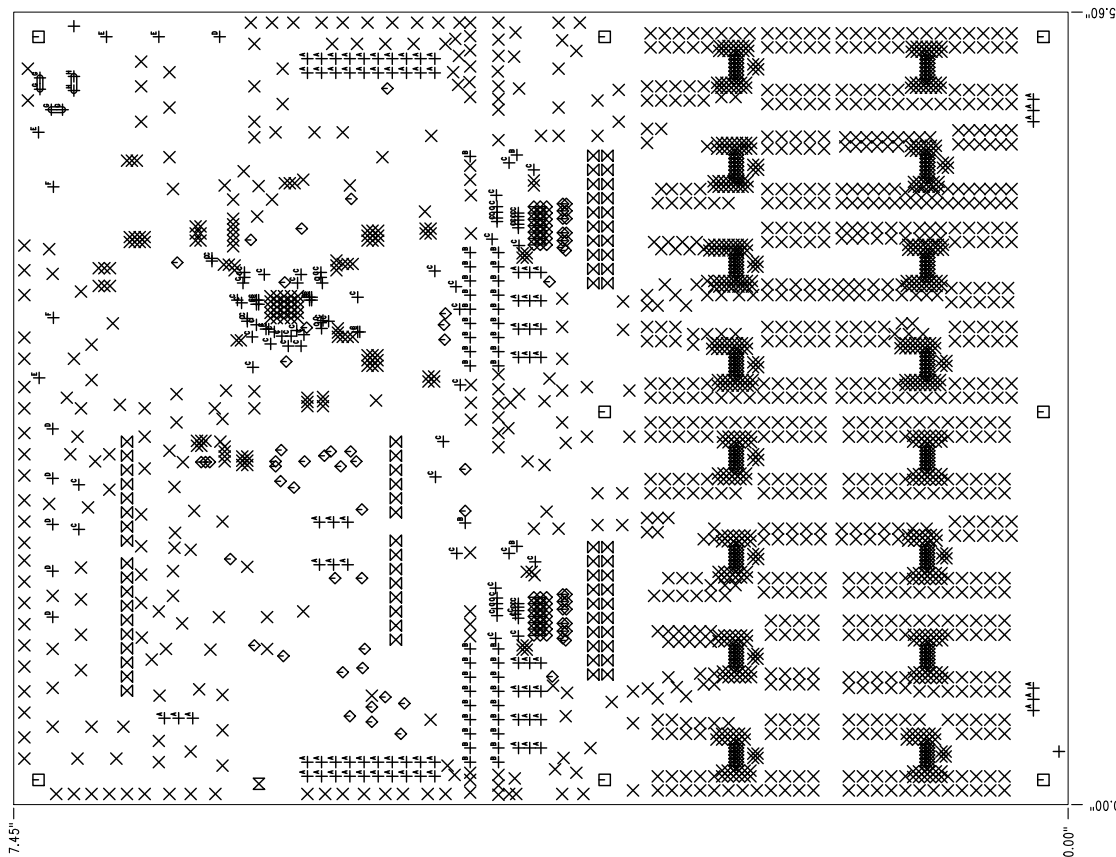


NOTES: UNLESS OTHERWISE SPECIFIED

1. FAB PER IPC-A-600.
2. MATERIAL:
 - LEAD FREE ASSEMBLY COMPLIANT, FR-370HR
 - FINISHED THICKNESS TO BE $0.082 \pm .005$
 - PLATING WITH MINIMUM OF 0.001" THICKNESS
 - 10 LAYERS, 10 COINER LAYERS.
 - STACK UP PER FIG. "LAYER STRUCTURE".
 - FLAMMABILITY RATING: 94 V-0 MINIMUM.
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN.
4. DRILLING:
 - DRILL HOLES PER SCHEDULE. PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
 - ALL HOLE SIZES ARE SPECIFIED AFTER PLATING.
 - HOLE LOCATION TOLERANCES ARE $\pm 0.003"$ IN RELATION TO CENTER
 - FOR VIAS SIZE $> 0.01"$, VIAS HOLES NEED TO BE PLUGGED AND COVERED WITH SOLDERMASK.
5. FINISH:
 - SOLDER USING LPI BOTH SIDES. COLOR BLACK.
 - SILKSCREEN LEGENDS SHALL BE WHITE NON-CONDUCTIVE EPOXY INK.
 - PLATING SHALL BE IMMERSION GOLD BOTH SIDES.
6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE. PAD SIZE CAN BE MODIFIED TO MEET END FINISH.
7. BOARDS SHALL BE RoHS COMPLIANT.
8. SCORING FOR PANELIZED PCB:



SIZE	QTY	SYM	PLATED	TOL
70	2	+	NO	+/-3
12	1581	X	YES	+/-3
187	8	□	NO	+/-3
10	334	◇	YES	+/-3
40	72	⊗	YES	+/-3
95	1	⊗	YES	+/-3
35	79	⊖ ^A	YES	+/-3
30	40	⊖ ^B	YES	+/-3
6	80	⊖ ^C	YES	+/-3
64	6	⊖ ^D	YES	+/-3
94	4	⊖ ^E	YES	+/-3
215	2	⊖ ^F	YES	+/-3
40 x 120	2	⊖ ^G	YES	+/-3
40 x 140	1	⊖ ^H	YES	+/-3



ADDITIONAL REQUIREMENT FOR PROTOTYPE FAB ONLY:

- ### 1. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).

ADDITIONAL REQUIREMENTS FOR PRODUCTION FAB ONLY:

1. PROVIDE COMPLIANCE CERTIFICATES FOR RoHS, REACH AND CONFLICT-FREE MINERALS.
2. SOLDERABILITY BOARD WITH TEST RESULTS.
3. OUTGOING INSPECTION REPORT (BASED ON ACTUAL MEASUREMENTS AND CROSS SECTION).
4. VACUUM PACKED WITH DESICCANT.
5. FULL PANEL WITH NO REJECT.

